

110V, 176A, 2.5m N-channel Power SGT MOSFET

JMSH1102QC

Features

- Excellent $R_{D(ON)}$ and Low Gate Charge
- 100% UIS Tested
- 100% Vds Tested
- Halogen-free; RoHS-compliant

Parameters	Value	Unit
V_{DS}	110	V
$V_{Gf(th)_Typ}$	3.1	V
$I_D(@V_{GS}=10V)$	176	A
$R_{D(ON)_Typ}$ GS	2.5	mΩ

Applications

- Load fwitch
- PWM Application

Device	Marking	MSL	Form	Package	Tube(pcs)	Per Carton (pcs)
JMSH1102QC-U				TO-220-3L		

	Parameter	Value	
V	Drain-to-fource Voltge	110	
V_{GS}	Gate-to-fource Voltge	±20	V
I_D	Continuous Drain Current	$T = 25^{\circ}C$	176
		$T_C = 100^{\circ}C$	125
	Pulsed Drain Current ⁽¹⁾		A
E	⁽²⁾	1488	
P_D		c	
		c	
T, T	Junction & fstorage Temperature Range	-55 to 150	°C

	⁽³⁾		

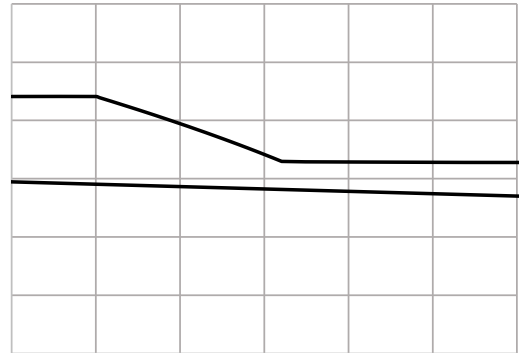
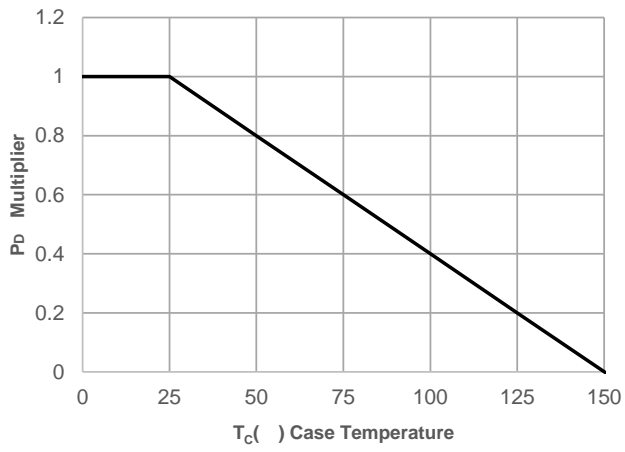
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

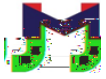
Symbol	Conditions	Min.	Typ.	Max.	Unit	
Off Characteristics						
$V_{(BR)DSS}$		110	-	-	V	
I_{DSS}		-	-	1.0	μA	
I_{GSS}		-	-	± 100	nA	
$V_{GS(th)}$		2.1	3.1	4.3	V	
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	-	2.5	3.5	$\text{m}\Omega$	
R_g	Gate Resistance	$f = 1\text{MHz}$	-	2.4	Ω	
C_{iss}		$V_{GS} = 0\text{V}, V_{DS} = 55\text{V}$	7411	10375	14007	pF
C_{oss}		$V_{GS} = 0\text{V}, V_{DS} = 55\text{V}$	1067	1494	2017	pF
C_{rss}		$f = 1\text{MHz}$	23	32	43	pF
Q_g		$V_{GS} = 0 \text{ to } 10\text{V}$	108	152	205	nC
Q_{gs}		$V_{DS} = 55\text{V}, I_D = 20\text{A}$	35	49	66	nC
Q_{gd}			24	34	46	nC
$t_{d(on)}$			-	44	-	ns
t_r		$V_{GS} = 10\text{V}, V_{DD} = 55\text{V}$	-	65	-	ns
$t_{d(off)}$		$I_D = 20\text{A}, R_{GEN} = 6.2\Omega$	-	128	-	ns
t_f			-	77	-	ns
I_S			-	-	176	A
I_{SM}			-	-	706	A
V_{SD}			-	-	1.2	V
t_{rr}			72	101	136	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F = 20\text{A}, di/dt = 100\text{A}/\mu\text{s}$	-	324	-	nC

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J=25^\circ\text{C}$, $V_{DD}=55\text{V}$, $V_{GS}=10\text{V}$, $R_G=25\text{ohm}$, $L=3\text{mH}$, $I_{AS}=31.5\text{A}$, $V_{DD}=0\text{V}$ during time in avalanche.
 3. $R_{\theta(jc)}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
 4. Pulse Test: Pulse Width 0.5%.

Typical Performance Characteristics

Figure 1: Power De-rating





Typical Performance Characteristics

Figure 5: Output Characteristics

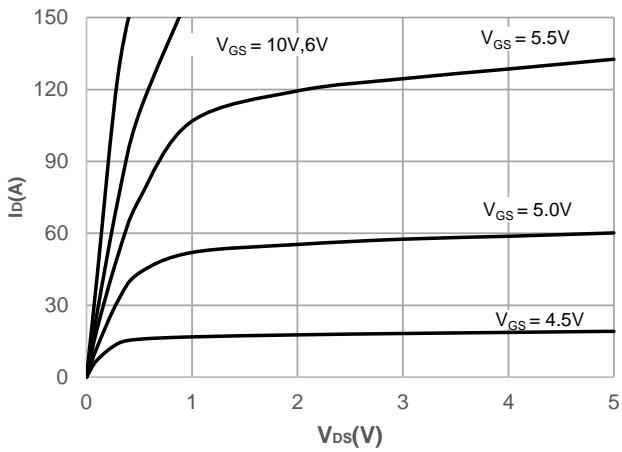


Figure 6: Typical Transfer Characteristics

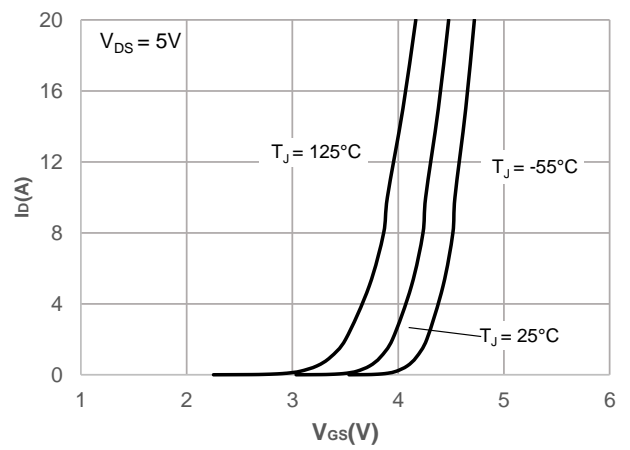


Figure 7: On-resistance vs. Drain Current

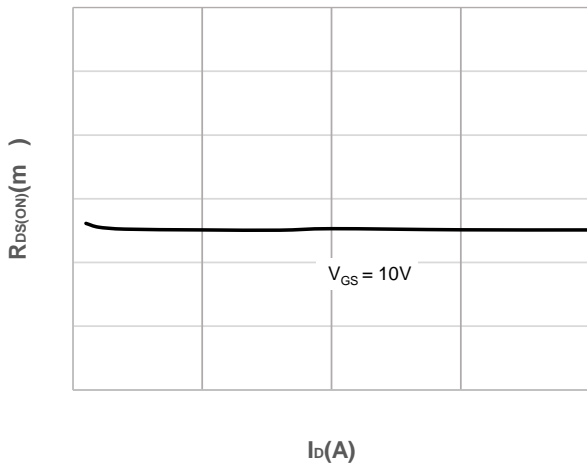


Figure 8: Body Diode Characteristics

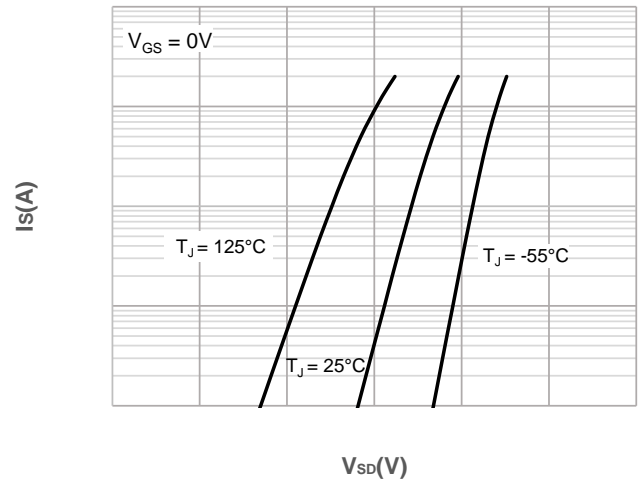


Figure 9: Gate Charge Characteristics

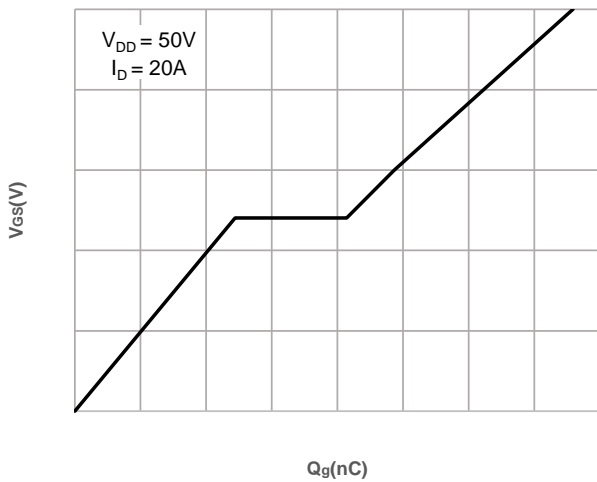
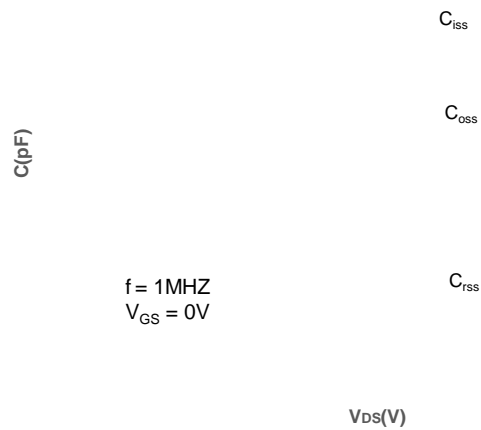


Figure 10: Capacitance Characteristics





Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

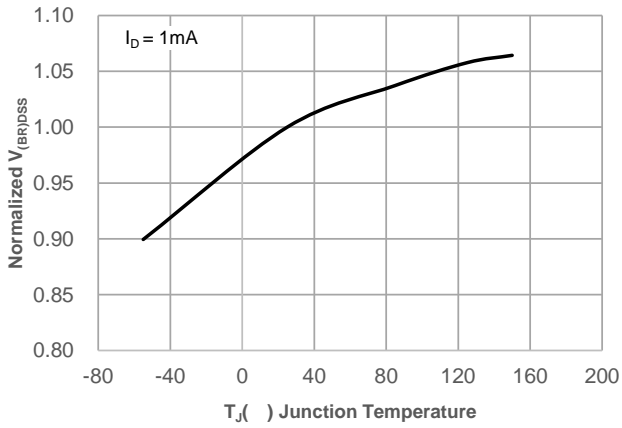


Figure 12: Normalized on Resistance vs. Junction Temperature

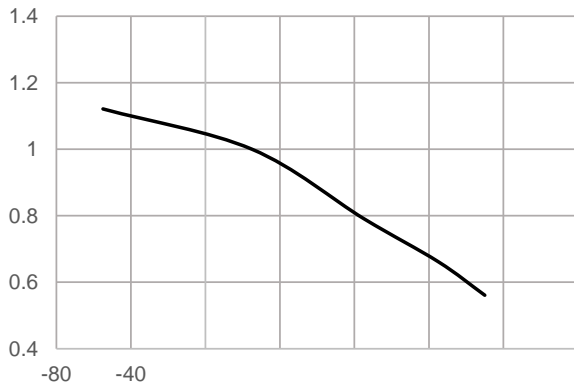
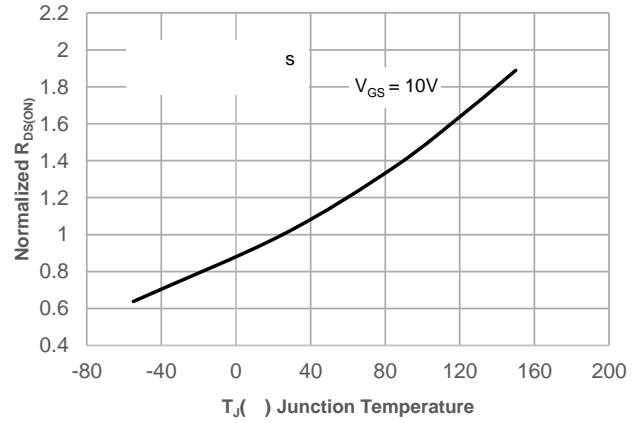


Figure 14: $R_{DS(on)}$ vs. V_{GS}

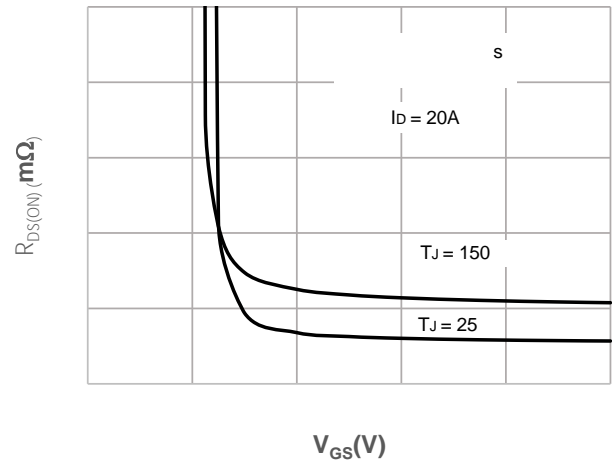
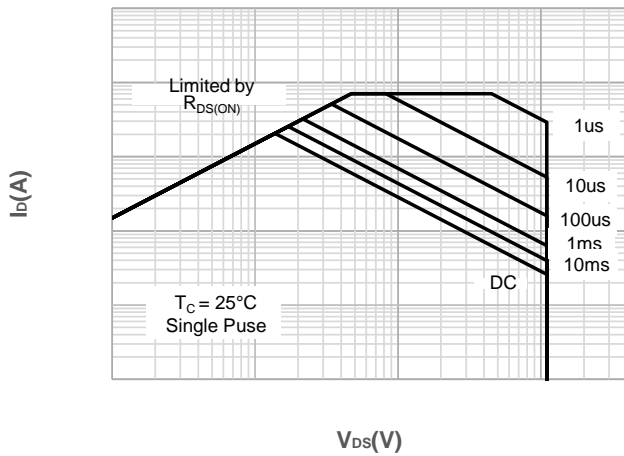


Figure 15: Maximum Safe Operating Area



Test Circuit

Package Mechanical Data(TO-220-3L)